

Please add new claims 19-25 as follows:

1 --19. (New) A package for mounting a semiconductor chip, comprising:
2 a leadframe, the leadframe comprising;
3 a chip paddle wherein a surface of the chip paddle is externally exposed from the package;
4 and
5 a plurality of internal leads surrounding the chip paddle, wherein a surface of each of the
6 plurality of internal leads is externally exposed from the package;
7 means for receiving encapsulating material for encapsulating the leadframe;
8 means for locking the encapsulating means to the chip paddle;
9 means for providing a fluid path for the encapsulating means during encapsulation of the leadframe;
10 and
11 means for removing fluid from the package .

1 20. (New) The package as set forth in claim 19, wherein the chip paddle has an etched portion on a
2 lower side area of the chip paddle.

1 21. (New) The package as set forth in claim 20, wherein the etched portion is about 10% to about
2 90% of the lower side area of the chip paddle.

1 22. (New) The package as set forth in claim 21, wherein the means for locking comprises the etched
2 portion.

1 23. (New) The package as set forth in claim 21, wherein the means for providing a fluid path comprises
2 the etched portion.

1 24. (New) The package as set forth in claim 21, wherein the means for removing fluid comprises the
2 etched portion.

1 25. (New) The package as set forth in claim 21, wherein the etched portion is located inside the
2 package body, the chip paddle and a lower surface of the plurality of internal leads are in a common plane,
3 and wherein the chip paddle is thicker than the at least one of the plurality of internal leads, the chip paddle
4 is bonded to a bottom surface of a semiconductor chip and at least one of the plurality of internal leads has
 an etched part at an end facing the chip paddle.--